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Kind regards,

Team Nexperia

# PHD3055E

## N-channel TrenchMOS standard level FET

Rev. 07 — 26 February 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

### 1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Suitable for high frequency applications due to fast switching characteristics

### 1.3 Applications

- DC-to-DC convertors
- Switched-mode power supplies

### 1.4 Quick reference data

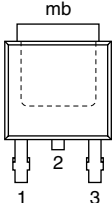
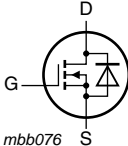
Table 1. Quick reference

| Symbol                         | Parameter                        | Conditions   | Min | Typ | Max  | Unit |
|--------------------------------|----------------------------------|--|-----|-----|------|------|
| $V_{DS}$                       | drain-source voltage             | $T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$   | -   | -   | 60   | V    |
| $I_D$                          | drain current                    | $T_{mb} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ;<br>see <a href="#">Figure 1</a> and <a href="#">3</a>                           | -   | -   | 10.3 | A    |
| $P_{tot}$                      | total power dissipation          | $T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>   | -   | -   | 33   | W    |
| <b>Dynamic characteristics</b> |                                  |  |     |     |      |      |
| $Q_{GD}$                       | gate-drain charge                | $V_{GS} = 10\text{ V}$ ; $I_D = 10\text{ A}$ ;<br>$V_{DS} = 44\text{ V}$ ; $T_j = 25\text{ °C}$ ;<br>see <a href="#">Figure 12</a> | -   | 3.2 | -    | nC   |
| <b>Static characteristics</b>  |                                  |  |     |     |      |      |
| $R_{DS(on)}$                   | drain-source on-state resistance | $V_{GS} = 10\text{ V}$ ; $I_D = 5.5\text{ A}$ ;<br>$T_j = 25\text{ °C}$ ;<br>see <a href="#">Figure 10</a> and <a href="#">11</a>  | -   | 120 | 150  | mΩ   |



## 2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                       | Simplified outline   | Graphic symbol  |
|-----|--------|-----------------------------------|--|---|
| 1   | G      | gate                              |  |  |
| 2   | D      | drain                             |  |   |
| 3   | S      | source                            |  |   |
| mb  | D      | mounting base; connected to drain |  |   |

**SOT428 (DPAK)**

[1] It is not possible to make connection to pin 2

## 3. Ordering information

Table 3. Ordering information

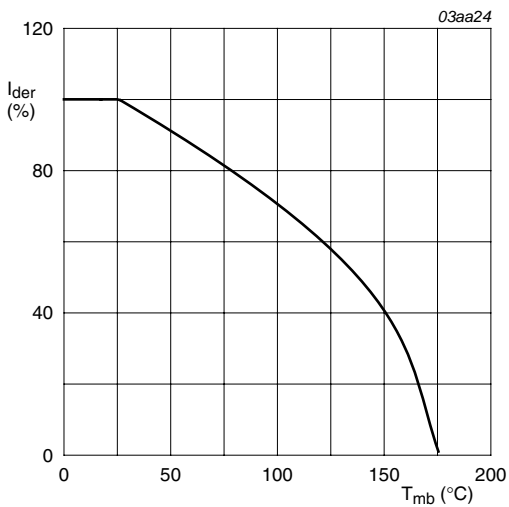
| Type number | Package |   | Version |
|-------------|---------|---|---------|
|             | Name    | Description   |         |
| PHD3055E    | DPAK    | plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) | SOT428  |

## 4. Limiting values

**Table 4. Limiting values**

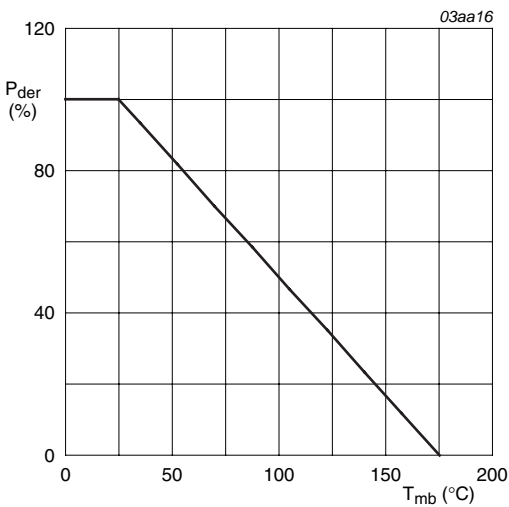
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol                      | Parameter                                     | Conditions   | Min | Max  | Unit               |
|-----------------------------|---|--|-----|------|--------------------|
| $V_{DS}$                    | drain-source voltage                          | $T_j \geq 25\text{ }^{\circ}\text{C}$ ; $T_j \leq 175\text{ }^{\circ}\text{C}$   | -   | 60   | V                  |
| $V_{DGR}$                   | drain-gate voltage                            | $T_j \geq 25\text{ }^{\circ}\text{C}$ ; $T_j \leq 175\text{ }^{\circ}\text{C}$ ; $R_{GS} = 20\text{ k}\Omega$  | -   | 60   | V                  |
| $V_{GS}$                    | gate-source voltage                           |  | -20 | 20   | V                  |
| $I_D$                       | drain current                                 | $V_{GS} = 10\text{ V}$ ; $T_{mb} = 100\text{ }^{\circ}\text{C}$ ; see <a href="#">Figure 1</a>   | -   | 7.3  | A                  |
|                             |   | $V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ }^{\circ}\text{C}$ ; see <a href="#">Figure 1</a> and <a href="#">3</a>  | -   | 10.3 | A                  |
| $I_{DM}$                    | peak drain current                            | $t_p \leq 10\text{ }\mu\text{s}$ ; pulsed; $T_{mb} = 25\text{ }^{\circ}\text{C}$ ; see <a href="#">Figure 3</a>  | -   | 41   | A                  |
| $P_{tot}$                   | total power dissipation                       | $T_{mb} = 25\text{ }^{\circ}\text{C}$ ; see <a href="#">Figure 2</a>   | -   | 33   | W                  |
| $T_{stg}$                   | storage temperature                           |  | -55 | 175  | $^{\circ}\text{C}$ |
| $T_j$                       | junction temperature                          |  | -55 | 175  | $^{\circ}\text{C}$ |
| <b>Source-drain diode</b>   |   |  |     |      |                    |
| $I_S$                       | source current                                | $T_{mb} = 25\text{ }^{\circ}\text{C}$  | -   | 10.3 | A                  |
| $I_{SM}$                    | peak source current                           | $t_p \leq 10\text{ }\mu\text{s}$ ; pulsed; $T_{mb} = 25\text{ }^{\circ}\text{C}$   | -   | 41   | A                  |
| <b>Avalanche ruggedness</b> |   |  |     |      |                    |
| $E_{DS(AL)S}$               | non-repetitive drain-source avalanche energy  | $V_{GS} = 10\text{ V}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $I_D = 3.3\text{ A}$ ; $V_{sup} \leq 25\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; unclamped; $t_p = 0.22\text{ ms}$ | -   | 25   | mJ                 |
| $I_{DS(AL)S}$               | non-repetitive drain-source avalanche current | $V_{GS} = 10\text{ V}$ ; $V_{sup} \leq 25\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; unclamped; see <a href="#">Figure 4</a>                  | -   | 10.3 | A                  |



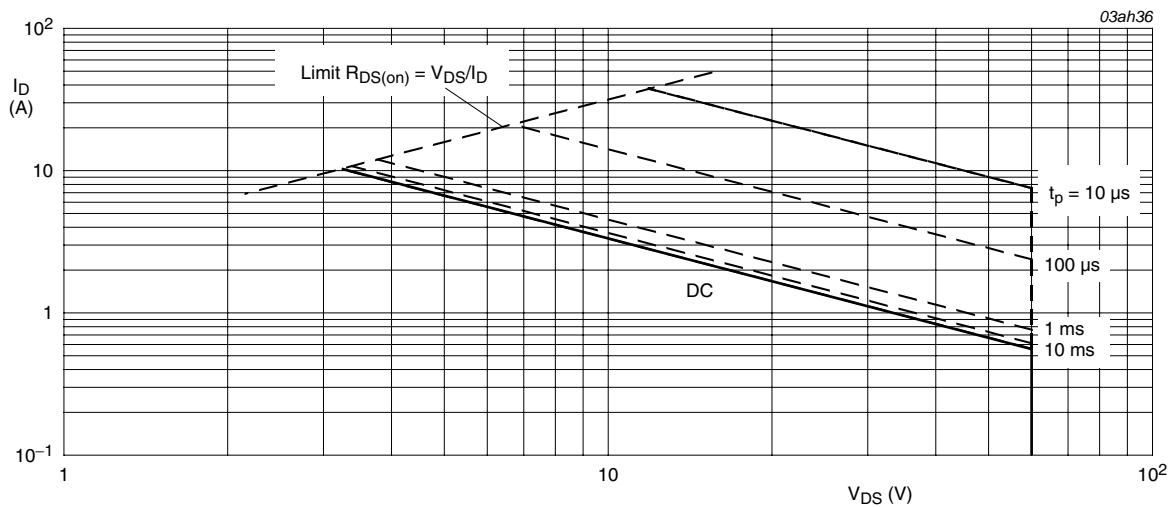
$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



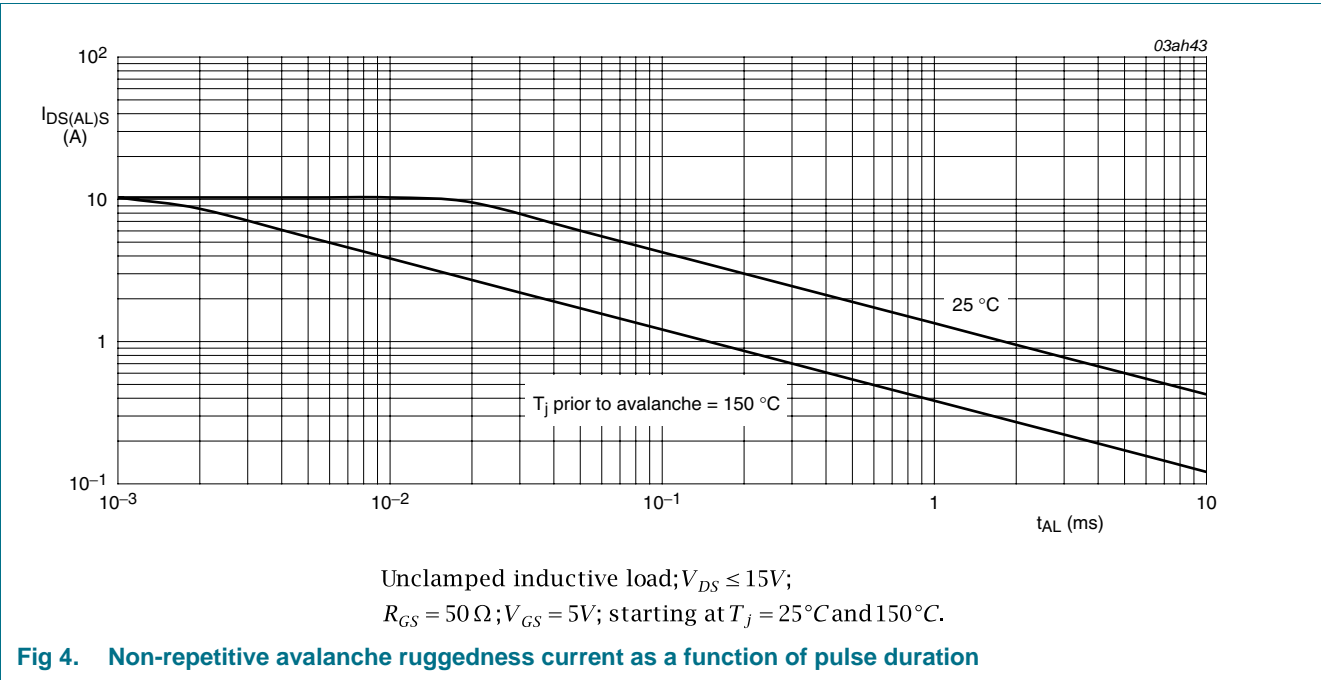
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{mb} = 25^{\circ}C$ ;  $I_{DM}$  is single pulse

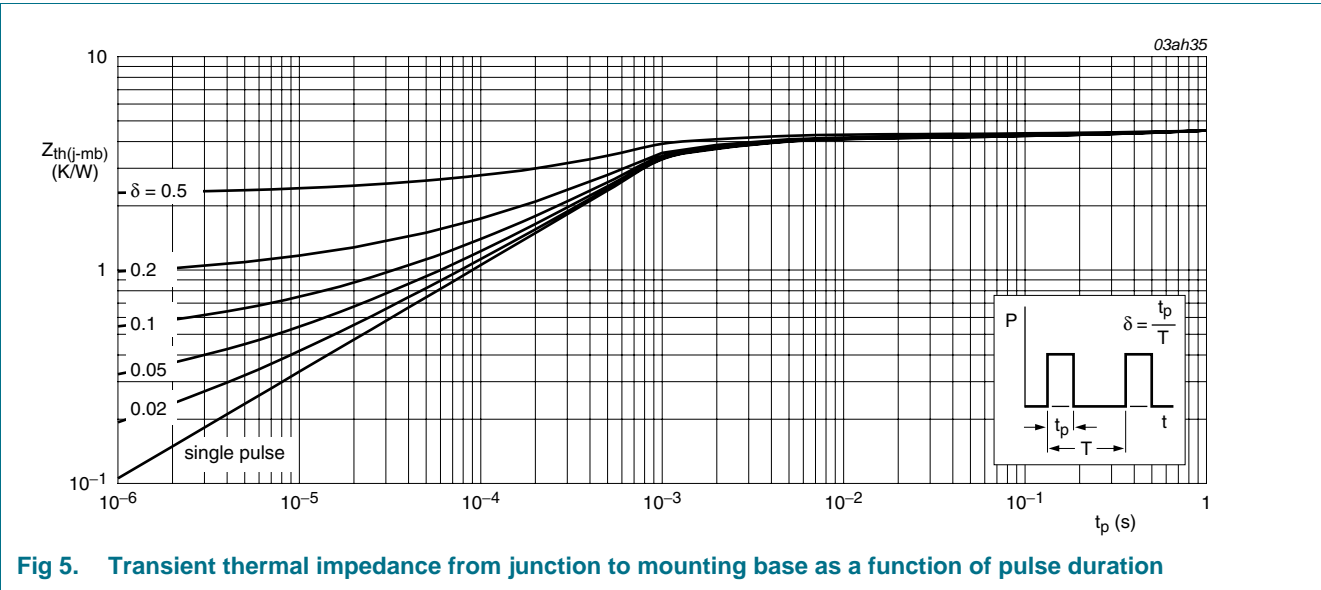
Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



5. Thermal characteristics

Table 5. Thermal characteristics

| Symbol         | Parameter   | Conditions                                 | Min | Typ | Max | Unit |
|----------------|---|--|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | see <a href="#">Figure 5</a>               | -   | -   | 4.5 | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       | SOT428 minimum footprint; mounted on a PCB | -   | 75  | -   | K/W  |
|                |   | SOT404 minimum footprint; mounted on a PCB | -   | 50  | -   | K/W  |



## 6. Characteristics

**Table 6. Characteristics**

| Symbol                  | Parameter                        | Conditions  | Min | Typ  | Max | Unit |
|-------------------------|----------------------------------|---|-----|------|-----|------|
| Static characteristics  |                                  |   |     |      |     |      |
| V <sub>(BR)DSS</sub>    | drain-source breakdown voltage   | I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = -55 °C  | 55  | -    | -   | V    |
|                         |                                  | I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C   | 60  | -    | -   | V    |
| V <sub>GS(th)</sub>     | gate-source threshold voltage    | I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 175 °C; see <a href="#">Figure 9</a>              | 1   | -    | -   | V    |
|                         |                                  | I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = -55 °C; see <a href="#">Figure 9</a>              | -   | -    | 6   | V    |
|                         |                                  | I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; see <a href="#">Figure 9</a>               | 2   | 3    | 4   | V    |
| I <sub>DSS</sub>        | drain leakage current            | V <sub>DS</sub> = 55 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C  | -   | -    | 500 | μA   |
|                         |                                  | V <sub>DS</sub> = 55 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C   | -   | 0.05 | 10  | μA   |
| I <sub>GSS</sub>        | gate leakage current             | V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C   | -   | 10   | 100 | nA   |
|                         |                                  | V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C  | -   | 10   | 100 | nA   |
| R <sub>DSon</sub>       | drain-source on-state resistance | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 5.5 A; T <sub>j</sub> = 175 °C; see <a href="#">Figure 10</a> and <a href="#">11</a> | -   | 250  | 315 | mΩ   |
|                         |                                  | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 5.5 A; T <sub>j</sub> = 25 °C; see <a href="#">Figure 10</a> and <a href="#">11</a>  | -   | 120  | 150 | mΩ   |
| Dynamic characteristics |                                  |   |     |      |     |      |
| Q <sub>G(tot)</sub>     | total gate charge                | I <sub>D</sub> = 10 A; V <sub>DS</sub> = 44 V; V <sub>GS</sub> = 10 V; T <sub>j</sub> = 25 °C; see <a href="#">Figure 12</a>  | -   | 5.8  | -   | nC   |
| Q <sub>GS</sub>         | gate-source charge               |   | -   | 1.5  | -   | nC   |
| Q <sub>GD</sub>         | gate-drain charge                |   | -   | 3.2  | -   | nC   |
| C <sub>iss</sub>        | input capacitance                | V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V; f = 1 MHz; T <sub>j</sub> = 25 °C; see <a href="#">Figure 13</a>               | -   | 190  | 250 | pF   |
| C <sub>oss</sub>        | output capacitance               |   | -   | 55   | 80  | pF   |
| C <sub>rss</sub>        | reverse transfer capacitance     |   | -   | 40   | 50  | pF   |
| t <sub>d(on)</sub>      | turn-on delay time               | V <sub>DS</sub> = 30 V; R <sub>L</sub> = 2.7 Ω; V <sub>GS</sub> = 10 V; R <sub>G(ext)</sub> = 5.6 Ω; T <sub>j</sub> = 25 °C   | -   | 3    | 10  | ns   |
| t <sub>r</sub>          | rise time                        |   | -   | 26   | 35  | ns   |
| t <sub>d(off)</sub>     | turn-off delay time              |   | -   | 8    | 15  | ns   |
| t <sub>f</sub>          | fall time                        |   | -   | 10   | 20  | ns   |
| Source-drain diode      |                                  |   |     |      |     |      |
| V <sub>SD</sub>         | source-drain voltage             | I <sub>S</sub> = 10 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; see <a href="#">Figure 14</a>                           | -   | 1.1  | 1.5 | V    |
| t <sub>rr</sub>         | reverse recovery time            | I <sub>S</sub> = 10 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 25 V; T <sub>j</sub> = 25 °C | -   | 32   | -   | ns   |
| Q <sub>r</sub>          | recovered charge                 |   | -   | 50   | -   | nC   |

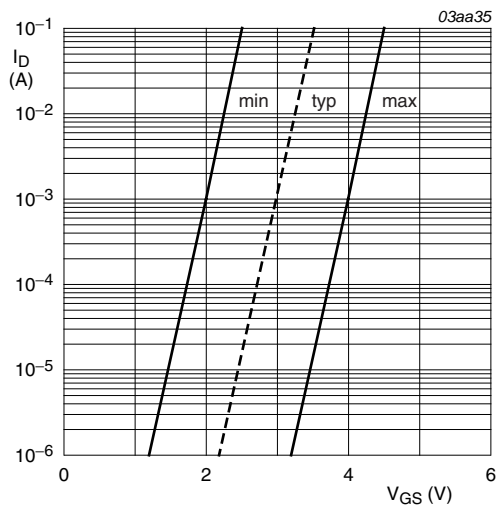


Fig 6. Sub-threshold drain current as a function of gate-source voltage

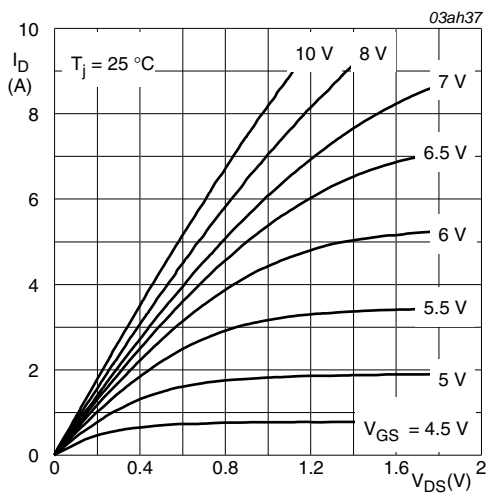


Fig 7. Output characteristics: drain current as a function of drain-source voltage; typical values

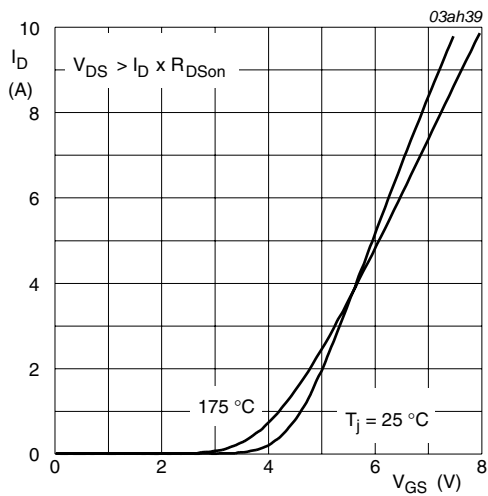


Fig 8. Transfer characteristics: drain current as a function of gate-source voltage; typical values

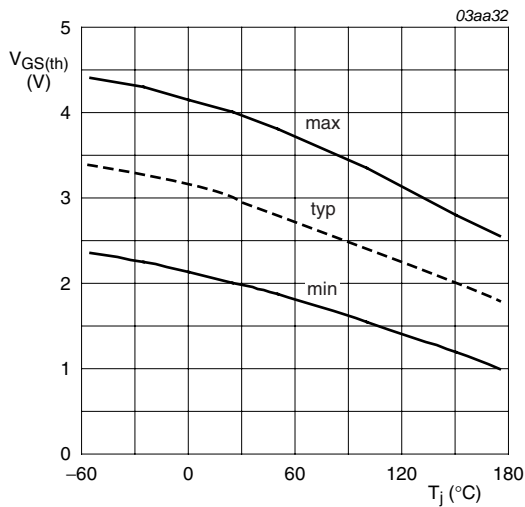
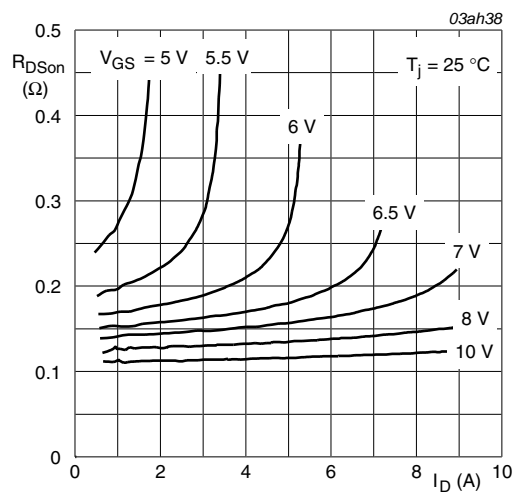


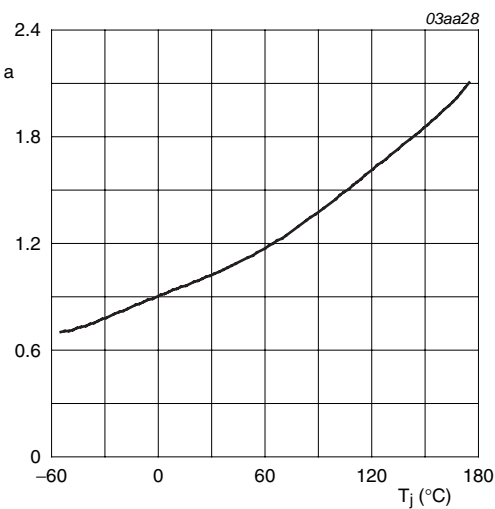
Fig 9. Gate-source threshold voltage as a function of junction temperature





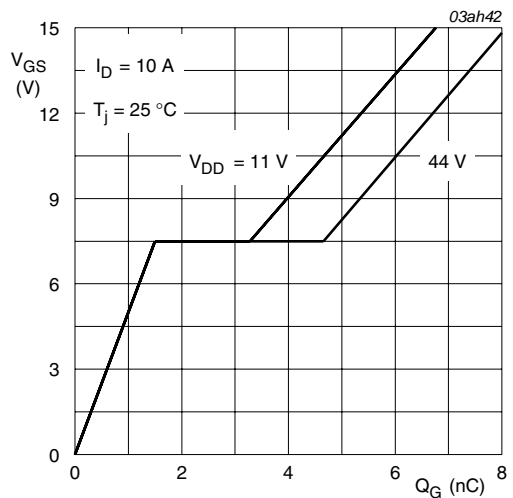
$T_J = 25\text{ }^\circ\text{C}$

Fig 10. Drain-source on-state resistance as a function of drain current; typical values



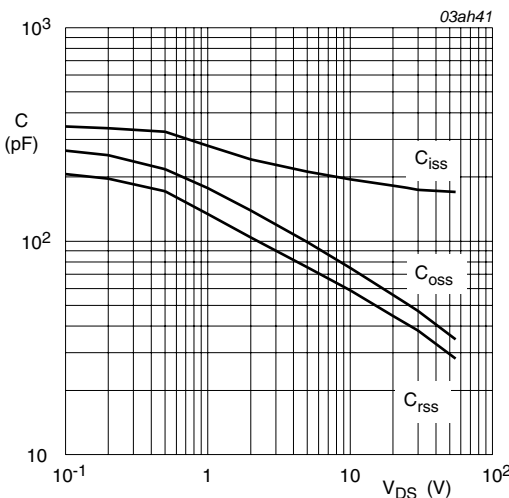
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 11. Normalized drain-source on-state resistance factor as a function of junction temperature



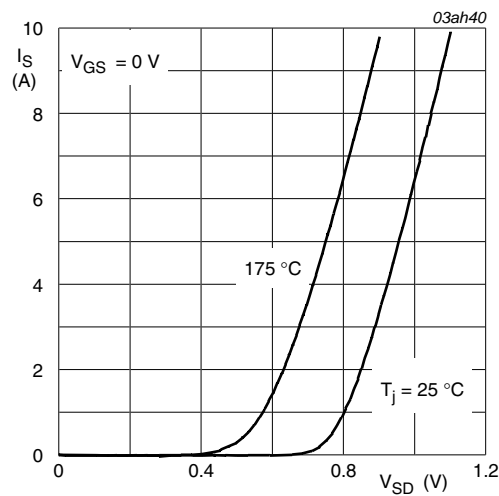
$I_D = 10\text{ A}; V_{DD} = 11\text{ V and } 44\text{ V}$

Fig 12. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}$  and  $175^\circ\text{C}$ ;  $V_{GS} = 0\text{ V}$

Fig 14. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) SOT428

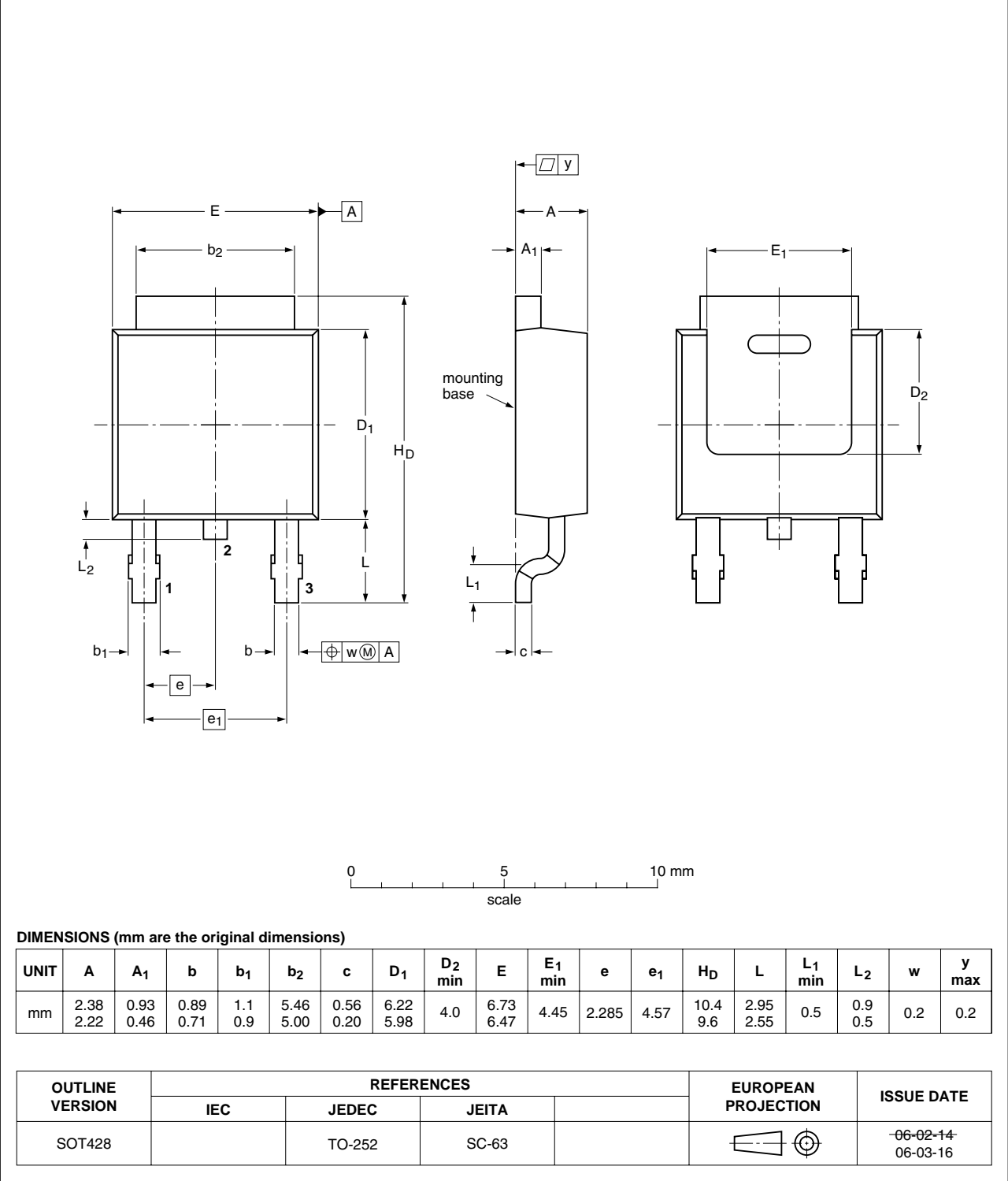


Fig 15. Package outline SOT428 (DPAK)

## 8. Revision history

Table 7. Revision history

| Document ID                         | Release date   | Data sheet status  | Change notice | Supersedes      |
|-------------------------------------|--|--------------------|---------------|-----------------|
| PHD3055E_7                          | 20100226   | Product data sheet | -             | PHP_PHD3055E-06 |
| Modifications:                      | <ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• Typenumber PHD3055E separated from datasheet PHP_PHD3055E-06.</li></ul> |                    |               |                 |
| PHP_PHD3055E-06<br>(9397 750 09354) | 20020325   | Product data       | -             | -               |

## 9. Legal information

### 9.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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